

# ABSTRACT OF THE DISCLOSURE

A semiconductor device comprises: a semiconductor chip;  
an extension portion which contacts the side surfaces of the  
semiconductor chip to thereby surround the semiconductor chip;  
5 an insulating film which is formed such that a part of each of  
the plurality of electrode pads is exposed; a plurality of wiring  
patterns individually electrically connected to each of the  
electrode pads, respectively and extended from the electrode  
pads to the upper side of the extension portion; and a plurality  
10 of external terminals provided over the wiring patterns in a  
region including the upper side of the extension portion.